ALPHA & OMEGA SEMICONDUCTOR

AONV190V70GA1

700V GaN Enhancement-mode Power Transistor

Features

- 700V GaN enhancement-mode transistor
- Normally-off design
- No Qrr (reverse recovery charge)
- Low Qg (gate charge), low Qoss (output charge)
- Integrated ESD protection

Applications

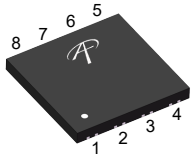
- PFC and PWM stages (LLC, FSFB, TTF) of Server, Telecom, Industrial, UPS, and Solar Inverters

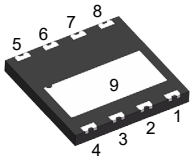
Product Summary at T_J = 25°C

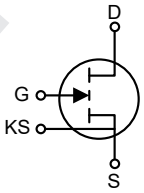
$V_{DS,\ max}$	700V
$R_{DS(on),\ max}$ @ V_{GS} = 6V	190mΩ
$Q_{g,\ typ}$ @ V_{DS} = 400V	2.8nC
$I_{D,\ pulse}$	20.5A
Q_{oss} @ V_{DS} = 400V	24.5nC
Q_{rr} @ V_{DS} = 400V	0nC

RoHS Compliant

Pin Configuration







Pin Information

Gate	Drain	Kelvin Source	Source
4	5, 6, 7, 8	3	1, 2, 9

Ordering Information

Ordering Part Number	Package Type	Form	Shipping Quantity
AONV190V70GA1	DFN8x8	Tape and Reel	1500

Contact local sales office for full product datasheet.

Absolute Maximum Ratings

(T_J = 25°C, unless otherwise noted)

Symbol	Parameter		AONV190V70GA1	Units
$V_{DS,\ max}$	Drain Source Voltage	V_{GS}=0V, T_J=-55°C to 150°C	700	V
$V_{DS,\ trans}$	Drain Source Voltage Transient (1)	V_{GS}=0V	800	
$V_{DS,\ pulse}$	Drain Source Voltage Pulsed (2)	T_C=25°C, total time < 10 hours	750	
		T_C=125°C, total time < 1 hour		
I_D	Continuous Drain Current	T_C=25°C	11.5	A
$I_{D,\ pulse}$	Pulsed Drain Current (3)	T_C=25°C, V_{GS}=6V, t_{pulse}=10µs	20.5	
		T_C=125°C, V_{GS}=6V, t_{pulse}=10µs	11.5	

Absolute Maximum Ratings

(T_J = 25°C, unless otherwise noted)

Symbol	Parameter		AONV190V70GA1	Units
V_{GS}	Gate Source Voltage, Continuous	T_J=-55°C to 150°C	-6 to 7	V
$V_{GS, pulse}$	Gate Source Voltage, Pulsed	T_J=-55°C to 150°C, t_{pulse}=50ns, f = 100kHz, open drain	-20 to 10	V
P_{tot}	Power Dissipation (4)	T_C=25°C	82	W
$T_{j, stg}$	Junction and Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ	Max	Note	Units
$R_{\theta JA}$	Thermal Resistance Junction-to-Ambient (5)	66			°C/W
$R_{\theta JC}$	Thermal Resistance Junction-to-Case	1.49	1.86 ???		°C/W
T_{sold}	Maximum Reflow Soldering Temperature	260		MSL3	°C

Electrical Characteristics

(T_J = 25°C, unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
STATIC PARAMETERS							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, I_D=12.2mA	T_J=25°C	1.2	1.7	2.5	V
			T_J=150°C		1.7		
I_{DSS}	Drain-Source Leakage Current	V_{DS}=700V, V_{GS}=0V	T_J=25°C		0.45	20	µA
			T_J=150°C		6		
I_{GSS}	Gate-Source Leakage Current	V_{GS}=6V, V_{DS}=0V, T_j=25°C			60		µA
$R_{DS(on)}$	Drain-Source On-State-Resistance	V_{GS}=6V, I_D=3.9A	T_J=25°C		138	190	mΩ
			T_J=150°C		300		
DYNAMIC							
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=400V, f=100kHz			96		pF
C_{oss}	Output Capacitance				30		
C_{rss}	Reverse Transfer Capacitance				0.5		
$C_{o(er)}$	Effective Output Capacitance Energy Related (6)	V_{GS}=0V, V_{DS}=0 to 400V			43		pF
$C_{o(tr)}$	Effective Output Capacitance Time Related (7)				60		
R_G	Gate Resistance	f=5MHz, open drain			5.8		Ω
SWITCHING							
Q_g	Gate Charge	V_{GS}=0 to 6V, V_{DS} =400V, I_D =3.9A			2.8		nC
Q_{gs}	Gate Source Charge				0.25		
Q_{gd}	Gate Drain Charge				1.1		
V_{plat}	Gate Plateau Voltage	V_{DS} = 400V, I_D =3.9A			2.2		V
Q_{oss}	Output Charge	V_{GS}=0V, V_{DS}=0 to 400V			24.5		nC
$t_{d(on)}$	Turn-On Delay Time	V_{DS} = 400 V; ID = 8 A; L = 318 µH; V_{GS} = 6 V; Ron = 10 Ω; Roff = 2 Ω;			1.4		ns
$t_{d(off)}$	Turn-Off Delay Time				1.7		
t_r	Rise Time				4		
t_f	Fall Time				4		

Electrical Characteristics *(Continued)*

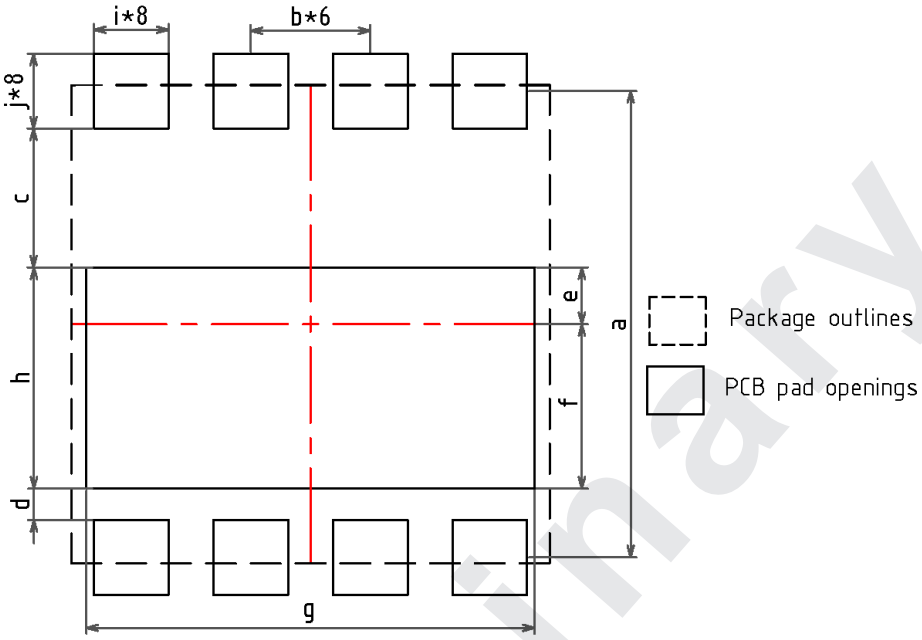
(T_J = 25°C, unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
REVERSE CONDUCTION							
V_{SD}	Source-Drain Reverse Voltage	V_{GS} = 0V, I_S = 3.9A, T_J = 25°C			2.6		V
$I_{S,\ pulse}$	Reverse Pulsed Current	V_{GS} = 6V, t_{pulse} = 10µs				20.5	A
Q_{rr}	Reverse Recovery Charge	V_R = 400V, I_S = 3.9A, dv/dt = 1kA/ µs			0		nC
t_{rr}	Reverse Recovery Time				0		ns
I_{rrm}	Peak Reverse Recovery Current				0		A

Notes:

1. $V_{DS,transient}$ is intended for non-repetitive events, t_{PULSE} < 200µs.
2. $V_{DS,pulse}$ is intended for repetitive pulse, t_{PULSE} < 100ns.
3. Limit was extracted from characterization test, not measured during production.
4. Power dissipation, and consequently max. current ratings are obtained using max. thermal resistance and max. temperature of 150°C.
5. R_{thJA} is determined with the device mounted on one square inch of copper pad, single layer 2oz copper on FR4 board.
6. $C_{O(er)}$ is the fixed capacitance that gives the same stored energy as C_{OSS} while VDS is rising from 0 to 400 V.
7. $C_{O(tr)}$ is the fixed capacitance that gives the same charging time as C_{OSS} while VDS is rising from 0 to 400 V.

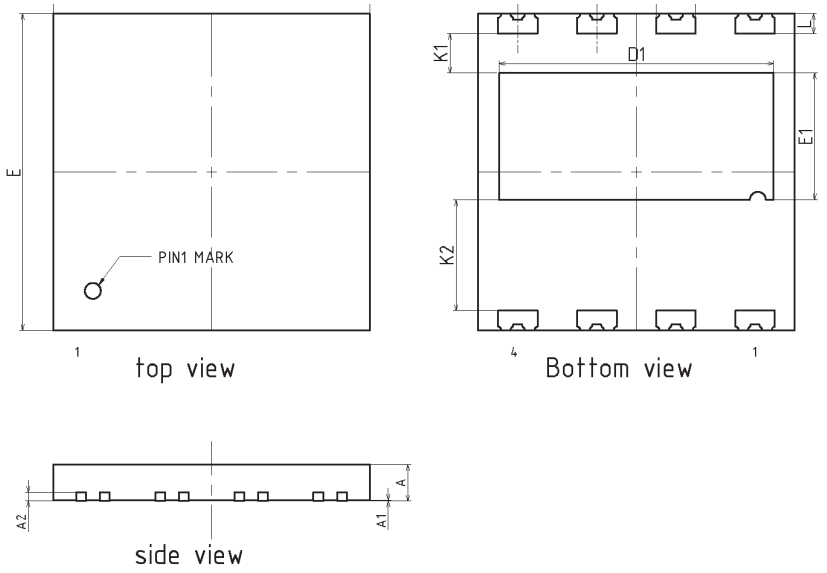
Recommended PCB Footprint



SYMBOL	DIMENSION	SYMBOL	DIMENSION
a	7.800	f	2.750
b	2.000	g	7.500
c	2.325	h	3.700
d	0.525	i	1.400
e	0.950	j	1.250

Notes:
(1)All dimension are in millimeters.
(2)Drawing is not to scale.

Package Dimensions, DFN8x8



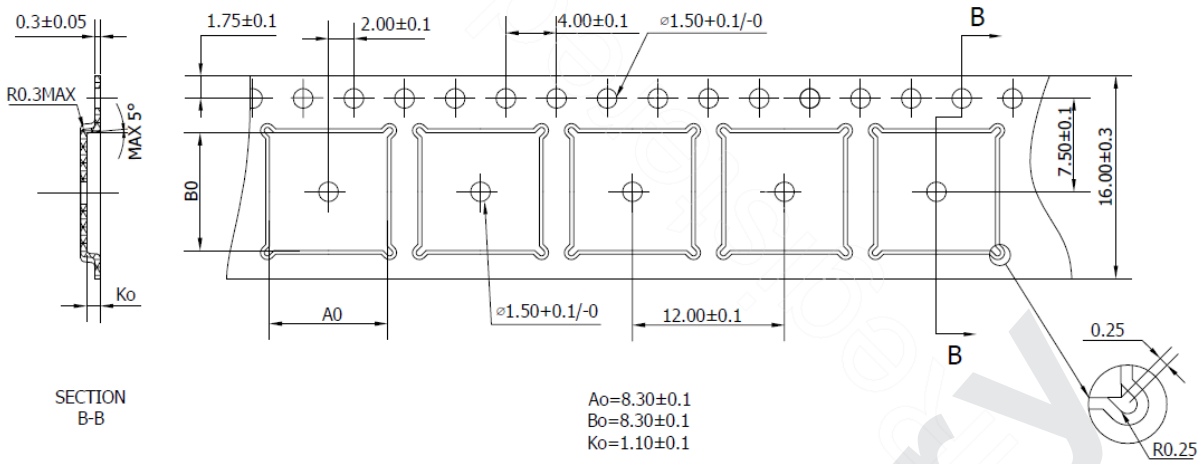
	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A2		0.203REF	
b	0.95	1.00	1.05
D		8.00 BSC	
D1	6.84	6.94	7.04
E		8.00 BSC	
E1	3.10	3.20	3.30
K1	0.90	1.00	1.10
K2	2.70	2.80	2.90
e		2.00 BSC	
L	0.40	0.50	0.60

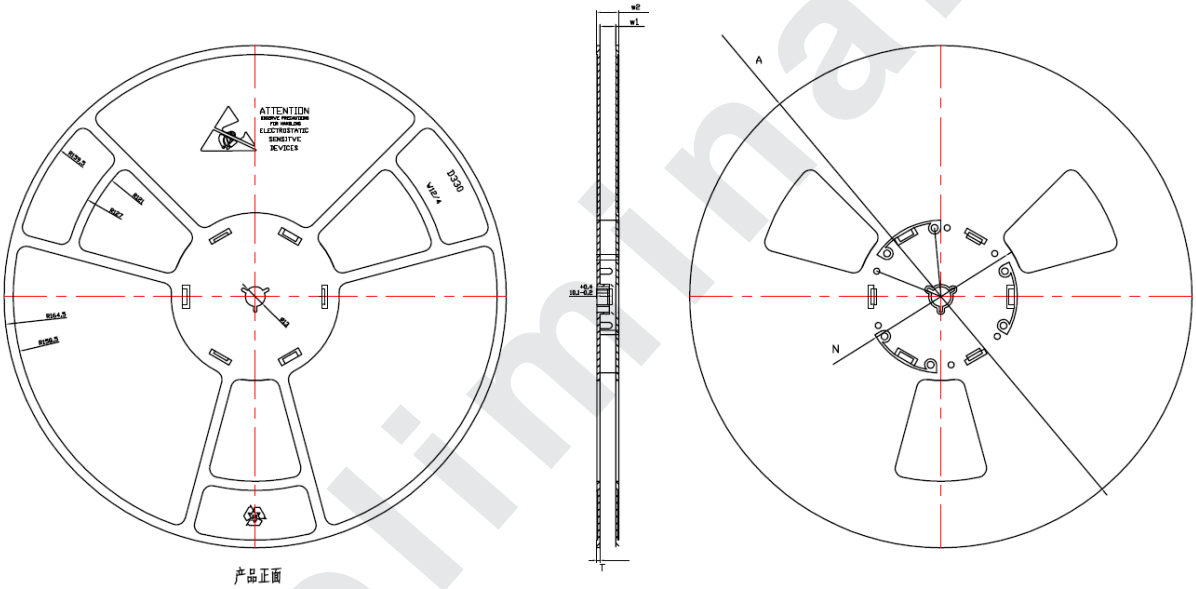
LOGO - AOS Logo
070V65GA1 - Part number code
F - Fab code
A - Assembly location code
Y - Year code
W - Week code
L&T - Assembly lot code

Notes:

1. Dimension and tolerance conform to ASME Y14.5-2009.
2. All dimensions are in millimeters.
3. Lead coplanarity will be 0.1 millimeters max.
4. Complies with JEDEC MO-229.
5. Drawing is not to scale.
6. Dimensions do not include mold protrusion.
7. Package outline exclusive of metal burr dimensions.

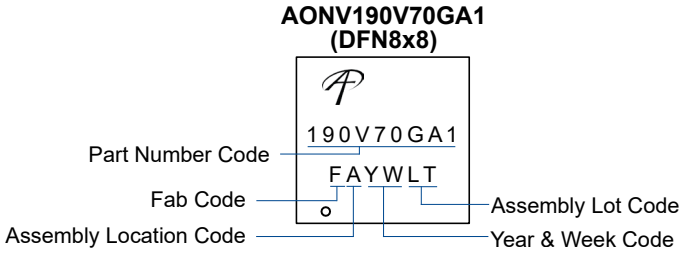
Tape and Reel Dimensions, DFN8x8





SYMBOL	DIMENSION(mm)		
	MIN	NOM	MAX
A	328	330	332
N	98	100	102
C	12.90	13.10	13.30
D	5.10	5.60	6.10
w1	16.40	16.40	18.40
w2	20.60	20.60	22.60
T	1.95	2.10	2.25
K	1.30	1.40	1.55

Part Marking



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